Special Issue

Ultra-Wideband Microwave/MM-Wave Components and Packaging

Message from the Guest Editor

The emerging wireless communication and sensor applications increasingly require higher data rates and larger bandwidths, which necessitate the development of practical ultra-wideband (UWB) microwave/millimeter-wave components, modules, and systems.

This Special Issue focuses on the analysis, design, and implementation of ultra-wideband microwave and mm-wave components for modern wireless communication and sensor applications.

- Analysis and design of ultra-wideband baluns and transitions
- Ultra-wideband component design techniques
- Design of ultra-wideband microwave/mm-wave power divider, couplers, filters, mixers, amplifiers, and transceivers
- Ultra-wideband RFIC/MMIC chips
- Various ultra-wideband microwave/mm-wave components
- Modeling and design of ultra-wideband antennas and their arrays
- Ultra-wideband MIMO antennas
- Ultra-wideband packaging and integration of active/passive RF devices.

Guest Editor

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closed (10 May 2021)

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Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

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manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.8 days after submission; acceptance to publication is undertaken in 2.4 days (median values for papers published in this journal in the first half of 2025).

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